

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT5815311

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEN-ICHI MIYANO	10/23/2019
FUKUMI TAKAHASHI	10/10/2019
YASUNORI ANETAI	10/10/2019
HITOSHI HAYANO	10/10/2019
HIDEAKI MONJUSHIRO	10/15/2019
SHIGEKI KATO	10/15/2019
TAKAYUKI SAEKI	10/15/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16612814
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NAME OF SUBMITTER:	SARAH PEDERSEN
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DATE SIGNED:	11/12/2019

Total Attachments: 3

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**COMBINED DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN APPLICATION****Title of
Invention****ELECTROLYTIC POLISHING METHOD AND DEVICE****DECLARATION**

As a below named inventor, I hereby declare that:

This declaration
is directed to:☐ The attached application, or☒ United States application or PCT international application
number PCT/JP2019/002257 filed on January 24, 2019.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C.
1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: "A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56."

ASSIGNMENT

In consideration of the good and valuable consideration paid, I hereby sell and assign to

MARUI GALVANIZING CO., LTD.

(Name of Assignee)

of 402 Kou, Shirahama-cho, Himeji-shi, Hyogo 672-8023, JAPAN

(Address of Assignee)

HIGASHI NIHON KIDENKAIHATSU CO., LTD.

(Name of Assignee)

of 5-19-10 Teshiromori, Morioka-shi, IWATE 020-0401, JAPAN, and

(Address of Assignee)

WING CO., LTD.

(Name of Assignee)

of 118-8 Akikozawa, Futago-cho, Kitakami-shi, Iwate 024-0104, JAPAN

(Address of Assignee)

(hereinafter designated as the Assignee) my entire right, title and interest for the United States as defined in 35 USC 100, for any invention set forth in the above-identified application.

I agree to execute all papers necessary in connection with this application for patent in the USPTO for the invention, and any continuation, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

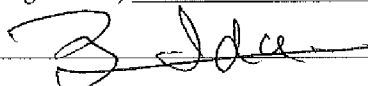
I agree to execute all papers necessary in connection with any post-grant proceeding which may occur in connection with this application or continuation, divisional or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such post-grant proceeding.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements, which includes the right to claim priority and the right to be granted a patent in any PCT Contracting State.

I agree to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

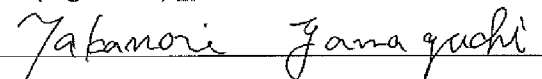
I hereby authorize and request the USPTO to issue any and all Letters Patents of the United States resulting from the application or any continuation, divisional or reissue applications thereof to the Assignee, as Assignee of my entire interest, and covenant that I have not executed, and will not execute, any agreement in conflict herewith.

First Inventor (Legal Name): Yoshiaki IDA

Signature: 

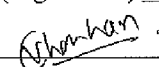
Date: Oct. 10, 2019

Second Inventor (Legal Name): Takanori YAMAGUCHI

Signature: 

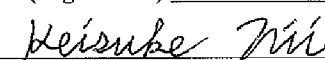
Date: Oct. 10, 2019

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Fourth Inventor (Legal Name): Keisuke NII

Signature: 

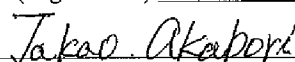
Date: Oct. 11, 2019

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Date: Oct. 10, 2019

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